

## IEEE 802.3 - Attendance and Affiliation Sheet

Dallas, TX - November 2013

Name	Employer	Affiliation	Mon	Tue	Wed	Thu	Credit
Abbas, Ghani	Ericsson AB	Ericsson AB	1	1	1	1	4
Abramson, David	Texas Instruments Incorporated	Texas Instruments Incorporated		1			1
Abughazaleh, Shadi		Hubbell Incorporated	1	1	1	1	4
Ahmad, Faisal		Akros Silicon Inc.	1	1	1		3
Ali, Hassan		Texas Instruments Incorporated		1	1	1	3
Allard, Michel	Cogeco Cable	Cogeco Cable	1	1	1	1	4
Anslow, Peter	Ciena Corporation	Ciena Corporation	1	1	1	1	4
Babenko, Oleksandr	Molex Incorporated	Molex Incorporated	1	1	1		3
Balasubramanian, Koussalya	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1	1	4
Baldwin, Thananya		Ixia	1	1	1		3
Barrass, Hugh	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1	1	4
Beaudoin, Denis	Texas Instruments Incorporated	Texas Instruments Incorporated	1	1	1	1	4
Beia, Christian	STMicroelectronics	STMicroelectronics	1	1	1	1	4
Belopolsky, Yakov	Self Employed	Bel Stewart Connector	1	1	1		3
Bennett, Michael	Lawrence Berkeley National Lab (LBNL)	Lawrence Berkeley National Lab (LBNL)	1	1	1	1	4
Bergey, Chris	Luxtera	Luxtera		1	1	1	3
Bernstein, Gary		Leviton Manufacturing Co.	1	1	1		3
Bliss, William	Broadcom Corporation	Broadcom Corporation	1	1	1	1	4
Booth, Brad	Dell	Microsoft Corporation	1	1	1	1	4
Bouda, Martin	Fujitsu Laboratories of America, Inc.	Fujitsu Laboratories of America, Inc.	1	1	1	1	4
Bower, Patricia		FUJITSU			1		1
Boyd, Edward		Broadcom Corporation		1	1	1	3
Braun, Ralf-Peter	Deutsche Telekom AG	Deutsche Telekom AG	1	1	1	1	4
Brophy, Timothy	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1	1	4
Brown, Alan	Aurora Networks, Inc.	Aurora Networks, Inc.	1	1	1	1	4
Brown, David	Semtech Ltd	Semtech Ltd		1	1	1	3
Brown, Matthew	Applied Micro (AMCC)	Applied Micro (AMCC)		1	1	1	3
Brown, Thomas	Vitesse Semiconductor	Vitesse Semiconductor Corporation	1	1	1	1	4
Brownlee, Phillip	Coilcraft, Inc.	Coilcraft, Inc.	1	1	1	1	4
Carlson, Steven	High-Speed Design Inc.	Broadcom Corporation	1	1	1	1	4

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Name	Employer	Affiliation	Mon	Tue	Wed	Thu	Credit
Carroll, Martin	Verizon Communications	Verizon	1		1	1	3
Casher, Patrick		Molex Incorporated	1	1	1	1	4
Chadha, Mandeep	Vitesse Semiconductor Corporation	Vitesse Semiconductor Corporation	1	1	1		3
Chalupsky, David	Intel Corporation	Intel Corporation	1	1	1		3
Cheng, Wheling		Juniper Networks, Inc.	1	1	1	1	4
Chou, Ger-Chih	Realtek Semiconductor Corp.	Realtek Semiconductor Corp.	1	1	1	1	4
Cibula, Peter	Intel Corporation	Intel Corporation	1	1	1	1	4
Cole, Christopher R		Finisar Corporation		1	1	1	3
Cook, Charles	CenturyLink, Inc.	CenturyLink, Inc.	1	1	1		3
Dai, Shaoan	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.		1	1	1	3
Dai, Y		Cox Communications Inc.		1	1	1	3
Dambrosia, John	Dell	Dell	1	1	1	1	4
Darling, Mike	Shaw Cablesystems	Shaw Cablesystems	1	1	1	1	4
Darshan, Yair	Microsemi Corporation	Microsemi Corporation	1	1			2
Dawe, Piers J G	Mellanox Technologies	Mellanox Technologies	1	1	1	1	4
Delveaux, William	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1		3
Dickinson, John		Bright House Networks		1	1	1	3
Diminico, Christopher	M C Communications, LLC	leoni	1	1	1		3
Dinh, Thuyen		Pulse-LINK Inc.		1	1	1	3
Donahue, Curtis		UNH-IOL	1	1	1	1	4
Dove, Daniel	Dove Networking Solutions	Applied Micro (AMCC)	1	1	1		3
Dudek, Michael	QLogic Corporation	QLogic Corporation	1	1	1	1	4
Dwellely, David	Linear Technology	Linear Technology	1	1	1	1	4
Elbakoury, Hesham	Nortel Networks	Huawei Technologies Co. Ltd	1	1	1	1	4
Erba, Simone	STMicroelectronics	STMicroelectronics	1	1	1	1	4
Estes, David		UNH-IOL	1	1	1	1	4
Ewen, John	JDS Uniphase Corporation	IBM	1	1	1	1	4
Farhoodfar, Arash	Cortina Systems	Cortina Systems	1	1	1	1	4
Flatman, Alan		LAN Technologies Corporation, Inc.	1	1	1		3
Forbes, Harry	Nexans Canada Inc.	Nexans Canada Inc.	1	1	1	1	4

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Frazier, Howard	Broadcom Corporation	Broadcom Corporation	1	1	1	1	4
Frosch, Richard	Phihong USA Inc,	Phihong USA Inc,		1	1	1	3
Fujikami, Craig		Spirent Communications	1	1	1		3
Garcia, Modesto	Texas Instruments Incorporated	Texas Instruments Incorporated		1	1	1	3
Gardner, Mike	Molex Incorporated	Molex Incorporated	1	1	1		3
Ge Hylander, Elyse		CommScope, Inc.		1	1	1	3
Goell, James		nano Precision Products	1	1	1	1	4
Green, Malcolm		Binoptics corp	1	1	1	1	4
Grimwood, Michael	Broadcom Corporation	Broadcom Corporation		1	1	1	3
Grow, Robert	INDEPENDENT	RMG Consulting	1	1	1	1	4
Gustlin, Mark	Xilinx	Xilinx	1	1	1	1	4
Hajduczenia, Marek	Bright House Networks	Bright House Networks	1	1	1	1	4
Hall, Eric		Aurion		1	1		2
Hamidy, Farid	Pulse Electronics	Pulse Electronics				1	1
Hammond, Bernard	TE Connectivity	TE Connectivity		1	1	1	3
Handal, Jeffry	Louisiana State University	Louisiana State University	1		1		2
Healey, Adam	LSI Corporation	LSI Corporation	1	1	1	1	4
Heath, Jeffrey	Linear Technology	Linear Technology		1	1	1	3
Herman, Carl	CommScope, Inc.	CommScope, Inc.	1	1	1	1	4
Hirth, Ryan	Broadcom Corporation	Broadcom Corporation		1	1	1	3
Hogenmueller, Thomas	Robert Bosch GmbH	Robert Bosch GmbH	1	1	1	1	4
Holden, Brian		Kandou Bus, S.A.	1	1	1	1	4
Horner, Rita	Synopsys, Inc.	Synopsys, Inc.	1	1	1	1	4
Hormmeyer, Bernd	Phoenix Contact	Phoenix Contact	1	1	1		3
Hou, Victor	Broadcom Corporation	Broadcom Corporation	1	1	1	1	4
Hua, Rui	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1	1	4
Huang, Liang-wei	Realtek Semiconductor Corp.	Realtek Semiconductor Corp.	1	1	1		3
Huber, Martin		MD Elektronik GmbH	1	1	1		3
ISHIBE, KAZUHIKO	Anritsu Company	Anritsu Company	1	1	1		3
Isono, Hideki	FUJITSU	Fujitsu Optical Components Limited	1	1	1	1	4

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Issenhuth, Tom	Microsoft Corporation	Microsoft Corporation		1	1	1	3
Iwaoka, Mitsuru	Yokogawa Electric Corporation	Yokogawa Electric Corporation	1	1		1	3
Jackson, Kenneth		Sumitomo Electric Industries, LTD	1	1	1	1	4
Jewell, Jack	Individual	CommScope, Inc.	1	1	1	1	4
Jiang, Wenbin	WJ Communications, Inc.	Cosemi Technologies		1	1	1	3
Jimenez, Andrew	Anixter Inc.	Anixter Inc.	1	1	1		3
Johnson, Peter		Sifos Technologies		1			1
Jones, Chad	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1		3
Jones, Doug		Comcast		1	1		2
Kaku, Shinkyō	Allied Telesis, Inc.	Allied Telesis, Inc.	1	1	1		3
Kawatsu, Yasuaki	Hitachi, Ltd.	Hitachi Cable Ltd	1	1	1	1	4
Kelsen, Michael	Time Warner Cable Inc.	Time Warner Cable Inc.	1	1	1	1	4
Khalil, Ahmad	TATA Communications						0
Kim, Yongbum	Broadcom Corporation	Broadcom Corporation				1	1
King, Jonathan	Finisar Corporation	Finisar Corporation	1	1	1	1	4
Kipp, Scott	Brocade Communications Systems, Inc.	Brocade Communications Systems, Inc.		1	1	1	3
Kliger, Avi	Broadcom Corporation	Broadcom Corporation	1	1	1		3
Knittle, Curtis	Cable Television Laboratories Inc. (Cable	Cable Television Laboratories Inc. (Cable	1	1	1	1	4
Kolesar, Paul	CommScope, Inc.	CommScope, Inc.	1	1	1	1	4
Kolze, Tom	Broadcom Corporation	Broadcom Corporation	1		1	1	3
Kono, Masashi	Hitachi, Ltd.	Hitachi, Ltd.	1	1	1	1	4
Kramer, Glen	Broadcom Corporation	Broadcom Corporation	1	1	1	1	4
Kunimitsu, Jocelyn		Spirent Communications	1	1	1		3
KUO, ALBERT	Realtek Semiconductor Corp.	Realtek Semiconductor Corp.		1	1	1	3
Lackner, Hans	QoSCom GmbH	QoSCom - Quality in Communications - G	1	1	1	1	4
Lane, Brett		Panduit Corp.		1	1		2
Larsen, Wayne	CommScope, Inc.	CommScope, Inc.	1	1	1		3
Laubach, Mark	Broadcom Corporation	Broadcom Corporation	1	1	1		3
Law, David	Hewlett-Packard Ltd	Hewlett-Packard Ltd	1	1	1	1	4
Lessard, Andre	CommScope, Inc.	CommScope, Inc.		1	1	1	3

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Le Van-Etter, Loni	3M	3M	1				1
Lewis, David	JDS Uniphase Corporation	JDS Uniphase Corporation		1	1	1	3
Li, Dou		Peking University		1	1		2
Li, Mike-Peng	Altera Corporation	Altera Corporation	1	1	1	1	4
Li, Shaohua		Brocade Communications Systems, Inc.		1	1	1	3
Lin, Ru	Shanghai Luster Teraband Photonics Co.	Shanghai Luster Teraband Photonics Co.		1	1	1	3
Lingle, Robert	OFS	OFS	1	1	1	1	4
Little, Paul		FUJITSU			1		1
Lounsbury, Robert		Rockwell Automation	1	1	1		3
Love II, Grayling		Leviton Manufacturing Co.		1			1
Lusted, Kent	Intel Corporation	Intel Corporation		1	1	1	3
Maguire, Valerie	The Siemon Company	The Siemon Company	1	1	1	1	4
Maki, Jeffery	Juniper Networks, Inc.	Juniper Networks, Inc.		1	1	1	3
MALKIMAN, YONATAN	Mellanox Technologies	Mellanox Technologies		1	1	1	3
Malette, Edwin	Bright House Networks	Bright House Networks	1	1	1	1	4
Marris, Arthur	Cadence Design Systems, Inc.	Cadence Design Systems, Inc.	1	1	1	1	4
Martinez, Joel		Altera Corporation		1	1		2
mash, chris	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.	1	1	1	1	4
Mason, Ralph		microchip		1			1
Matheus, Kirsten	BMW Group	BMW Group	1	1	1	1	4
Mcdermott, Thomas	FUJITSU	Fujitsu	1	1	1	1	4
McDonough, John	NEC Corporation	NEC America	1	1	1	1	4
McLean, Andrew		Texas Instruments Incorporated		1	1		2
Meier, Wolfgang	Emerson Network Power	Emerson Network Power		1	1	1	3
Mellitz, Richard	Intel Corporation	Intel Corporation		1	1		2
Meurer, Martin		MD Elektronik GmbH	1	1	1		3
Misek, Brian	Avago Technologies	Avago Technologies		1	1	1	3
Mohammadian, Ardeshir		Brocade Communications Systems, Inc.		1	1		2
Montreuil, Leo	Broadcom Corporation	Broadcom Corporation		1	1	1	3
Mooney, Paul	Spirent Communications	Spirent Communications	1	1	1		3

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Moore, Charles	Avago Technologies	Avago Technologies	1	1	1	1	4
Moorwood, Charles	Infinera Corporation	Infinera Corporation	1	1	1	1	4
Mueller, Thomas	Rosenberger Hochfrequenztechnik Gmb	Rosenberger Hochfrequenztechnik Gmb		1	1	1	3
Muir, Ron		Japan Aviation Electronics Ind., LTD. (JAE		1	1	1	3
Murray, Dale	LightCounting	LightCounting LLC	1	1	1	1	4
Muth, Karlheinz	Intel Corporation	Texas Instruments Incorporated		1	1		2
Nakamoto, Edward	Spirent Communications	Spirent Communications		1	1	1	3
Ng, Lup	Cortina Systems	Cortina Systems		1	1		2
Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1	1	4
Nolan, John	QLogic Corporation	QLogic Corporation	1	1	1	1	4
Noll, Kevin	Time Warner Cable Inc.	Time Warner Cable Inc.		1	1	1	3
Nordin, Ronald	Panduit Corp.	Panduit Corp.		1	1	1	3
Nouri, Ahmad	Broadcom Corporation	Broadcom Corporation	1	1	1		3
Ofelt, David	Juniper Networks, Inc.	Juniper Networks, Inc.	1	1	1	1	4
Ogura, Ichiro		PETRA	1	1	1	1	4
Palkert, Thomas	EIC	Xilinx-Luxtera-Molex	1	1	1	1	4
Pandey, Sujan	NXP Semiconductors	NXP Semiconductors	1	1	1	1	4
Panguluri, Sesa	Broadcom Corporation	Broadcom Corporation	1	1	1	1	4
Pardo, Carlos	Knowledge Development for POF SL	KDPOF		1	1	1	3
Patel, Pravin		IBM		1	1	1	3
Payne, Robert		Texas Instruments Incorporated		1	1		2
Pepeljugoski, Petar	IBM	IBM	1	1	1	1	4
Pepper, Gerald		Ixia	1	1	1		3
Peters, Michael	Sumitomo Electric Industries, LTD	Sumitomo Electric Industries, LTD		1	1	1	3
Petrilla, John	Avago Technologies	Avago Technologies	1	1	1		3
Pimpinella, Rick	Panduit Corp.	Panduit Corp.	1	1	1		3
Poehmerer, Rainer		LEONI	1	1	1	1	4
Powell, William	ALCATEL-LUCENT	ALCATEL-LUCENT	1	1	1	1	4
Prodan, Richard	Broadcom Corporation	Broadcom Corporation	1		1	1	3
Rabinovich, Rick		ALCATEL-LUCENT	1	1	1	1	4

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Name	Employer	Affiliation	Mon	Tue	Wed	Thu	Credit
Rahman, Saifur	Comcast	Comcast	1	1	1		3
Rahman, Syed	Huawei R&D USA	Huawei R&D USA		1	1	1	3
Remein, Duane	FiberHome Technologies Group	Huawei Technologies Co. Ltd	1	1	1		3
Renteria, Victor		Bel Fuse		1			1
Ressl, Michael	Hitachi, Ltd.	Hitachi Cable America Inc.	1	1	1	1	4
Rimboim, Poldi	Microsemi Corporation	Microsemi Corporation		1	1	1	3
Robertson, Max		Texas Instruments Incorporated	1	1	1		3
Rotolo, Salvatore	STMicroelectronics	STMicroelectronics	1	1	1	1	4
Rush, Brian		Maxim Integrated Products		1	1		2
Salinger, Jorge	Comcast	Comcast	1	1	1		3
sambasivan, sam	AT&T	AT&T	1	1	1		3
Schindler, Fred	Seen Simply	Seen Simply	1	1	1	1	4
Schmitt, Matthew	Cable Television Laboratories Inc. (Cable	Cable Television Laboratories Inc. (Cable		1	1	1	3
Schneelee, Stefan	EADS	EADS	1	1	1	1	4
Scruton, Peter		University of New Hampshire InterOpera	1	1	1	1	4
Seefried, Jeff		Leviton Manufacturing Co.	1	1			2
Shan, Peijun		Acacia Communications		1	1	1	3
Shanbhag, Megha	Tyco Electronics Corporation	TE Connectivity		1	1	1	3
Shang, Song	Semtech	Semtech Corp		1	1	1	3
Shellhammer, Stephen	Qualcomm Incorporated	Qualcomm Incorporated		1	1		2
Shen, Bazhong	Broadcom Corporation	Broadcom Corporation	1	1	1	1	4
Shrikhande, Kapil	Force 10 Networks, Inc.	Dell	1	1	1	1	4
Solomon, Joe	Comcast	Comcast	1	1	1	1	4
Sommers, Scott	Molex Incorporated	Molex Incorporated	1	1	1		3
Sone, Yoshiaki		Nippon Telegraph and Telephone Corpor	1	1	1	1	4
Song, Haoyu		Huawei R&D USA		1	1	1	3
Song, Xiaolu		Huawei Technologies Co. Ltd	1	1	1	1	4
Sparacin, Daniel	Aurrion	Aurrion		1	1		2
Sparrowhawk, Bryan	Leviton Manufacturing Co.	Leviton Manufacturing Co.	1	1	1	1	4
Stassar, Peter	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1	1	4

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Stencel, Leonard		Bourns, Inc	1	1	1	1	4
Sun, Yanbin	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1		3
Suzuki, Ken-Ichi	Nippon Telegraph and Telephone Corpor	NTT	1	1	1	1	4
Swanson, Steven	Corning Incorporated	Corning Incorporated	1	1	1		3
Szeto, William	Xtera Communications	3C Systems Company	1	1	1	1	4
TAJIMA, AKIO	NEC Corporation	NEC Corporation	1	1	1	1	4
TAKAHARA, TOMOO		FUJITSU LABORATORIES LIMITED	1	1	1	1	4
Tan, Alexander		Marvell Semiconductor, Inc.	1	1	1	1	4
Tanaka, Keiji		KDDI R&D Laboratories	1	1	1		3
Tanaka, Toshiki	FUJITSU LABORATORIES LIMITED	FUJITSU LABORATORIES LIMITED	1	1	1	1	4
TAZEBAY, MEHMET	Broadcom Corporation	Broadcom Corporation	1	1	1	1	4
Teipen, Brian		ADVA Optical Networking Ltd.	1	1	1	1	4
Teixeira, Antonio	Nokia Siemens Networks	Nokia Siemens Networks		1	1	1	3
Teixeira, Antonio L	Nokia Siemens Networks	Nokia Siemens Networks		1	1	1	3
Thompson, Geoffrey	GraCaSI S.A.	GraCaSI S.A.	1	1	1	1	4
Timmins, Ian	Optical Cable Corporation (OCC)	Optical Cable Corporation (OCC)		1	1		2
Tojo, Koichi		MegaChips Corporation	1	1	1	1	4
Tracy, Nathan	TE Connectivity	TE Connectivity	1	1	1	1	4
Tremblay, David	Hewlett-Packard Ltd	Hewlett-Packard Company		1	1	1	3
Tretter, Albert	Siemens AG	Siemens AG	1	1	1	1	4
Triess, Burkhard	ETAS GmbH	Bosch/ETAS	1				1
Trowbridge, Stephen	ALCATEL-LUCENT	ALCATEL-LUCENT	1	1	1	1	4
TSENG, WEN-CHENG		MediaTek Inc.	1	1	1	1	4
Ugolini, Alan		US Conec, Ltd.	1	1	1	1	4
Ulm, John	Motorola Mobility	Motorola Mobility	1	1	1		3
Ulrichs, Ed		Source Photonics	1	1	1	1	4
Umnov, Alexander	FUJITSU	Huawei Technologies Co. Ltd	1	1	1		3
Unmehopa, Musa	Philips Electronics	Philips Electronics	1	1	1	1	4
Vaden, Sterling	Optical Cable Corporation (OCC)	Optical Cable Corporation (OCC)	1	1		1	3
Vallance, R.		nanoPrecision Products		1	1	1	3



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Valle, Stefano	STMicroelectronics	STMicroelectronics	1	1	1	1	4
Vanderlaan, Paul	Nexans Canada Inc.	Berk-Tek LLC	1	1	1	1	4
VITTAL, BALASUBRAMANIAN	Dell	Dell		1	1	1	3
Wagner, Robert	Panduit Corp.	Panduit Corp.		1	1	1	3
Walker, Clinton	Intel Corporation	Intel Corporation			1	1	2
Wang, Robert	Intel Corporation	Intel Corporation	1	1	1	1	4
Wang, Tongtong		Huawei Technologies Co. Ltd		1	1	1	3
Wang, Xiaofeng	PMC-Sierra, Inc.	Qualcomm Incorporated	1	1	1	1	4
Wang, Xinyuan		Huawei Technologies Co. Ltd		1	1	1	3
WANG, ZHONG FENG		Broadcom Corporation	1	1	1	1	4
Warke, Nirmal	Texas Instruments Incorporated	Texas Instruments Incorporated	1	1	1		3
Warren, David	Hewlett-Packard Development Company	Hewlett-Packard Development Company	1	1	1	1	4
Welch, Brian		Luxtera		1	1	1	3
Welch, James	IneoQuest	IneoQuest		1	1	1	3
Wendt, Matthias	Philips Electronics	Philips Electronics	1	1	1	1	4
Winkel, Ludwig	Siemens AG	Siemens AG	1	1	1	1	4
Wolfe, Ronald		Aurora Networks, Inc.		1	1		2
Woodruff, William	Aquantia	Broadcom Corporation	1	1	1		3
Wu, Peter	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.		1	1	1	3
Xu, Hongchun		Accelink Technologies	1	1	1	1	4
Xu, Yu	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd		1	1		2
Yseboodt, Lennart		Philips Electronics	1		1	1	3
yu, cc		MediaTek Inc.	1	1	1	1	4
Yuan, Liquan	ZTE Corporation	ZTE Corporation	1	1	1	1	4
Yurko, Garold	TE Connectivity	TE Connectivity		1	1	1	3
Zambell, Andrew	FCI USA Inc.	FCI USA Inc.	1	1	1	1	4
Zebhauser, Martin		Rosenberger		1			1
Zhang, Jin	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.	1	1	1	1	4
zhao, yuping		School of EECS, Peking University, Beijing		1	1		2
Zhuang, Yan		Huawei Technologies Co. Ltd	1	1	1		3

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<b>Name</b>	<b>Employer</b>	<b>Affiliation</b>	<b>Mon</b>	<b>Tue</b>	<b>Wed</b>	<b>Thu</b>	<b>Credit</b>
Zimmerman, George	CME Consulting	Aquantia and CommScope, Inc.	1	1	1	1	4
Zivny, Pavel	Tektronix, Inc.	Tektronix		1	1	1	3
Zou, Gaoling		Maxim Integrated Products				1	1